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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	CANbus, I ² C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, LCD, POR, PWM, WDT
Number of I/O	63
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 12bit SAR; D/A 12bit
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TJ)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32tg11b540f64iq80-a

4.1.2.1 General Operating Conditions

Table 4.2. General Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating ambient temperature range ⁶	T _A	-G temperature grade	-40	25	85	°C
		-I temperature grade	-40	25	125	°C
AVDD supply voltage ²	V _{AVDD}		1.8	3.3	3.8	V
VREGVDD operating supply voltage ^{2 1}	V _{VREGVDD}	DCDC in regulation	2.4	3.3	3.8	V
		DCDC in bypass, 50mA load	1.8	3.3	3.8	V
		DCDC not in use. DVDD externally shorted to VREGVDD	1.8	3.3	3.8	V
VREGVDD current	I _{VREGVDD}	DCDC in bypass, T ≤ 85 °C	—	—	200	mA
		DCDC in bypass, T > 85 °C	—	—	100	mA
DVDD operating supply voltage	V _{DVDD}		1.62	—	V _{VREGVDD}	V
IOVDD operating supply voltage	V _{IOVDD}	All IOVDD pins ⁵	1.62	—	V _{VREGVDD}	V
DECOUPLE output capacitor ^{3 4}	C _{DECOUPLE}		0.75	1.0	2.75	μF
HFCORECLK frequency	f _{CORE}	VSCALE2, MODE = WS1	—	—	48	MHz
		VSCALE2, MODE = WS0	—	—	25	MHz
		VSCALE0, MODE = WS1	—	—	20	MHz
		VSCALE0, MODE = WS0	—	—	10	MHz
HFCLK frequency	f _{HFCLK}	VSCALE2	—	—	48	MHz
		VSCALE0	—	—	20	MHz
HFSRCCLK frequency	f _{HFSRCCLK}	VSCALE2	—	—	48	MHz
		VSCALE0	—	—	20	MHz
HFBUSCLK frequency	f _{HFBUSCLK}	VSCALE2	—	—	48	MHz
		VSCALE0	—	—	20	MHz
HFPERCLK frequency	f _{HFPERCLK}	VSCALE2	—	—	48	MHz
		VSCALE0	—	—	20	MHz
HFPERBCLK frequency	f _{HFPERBCLK}	VSCALE2	—	—	48	MHz
		VSCALE0	—	—	20	MHz
HFPERCCLK frequency	f _{HFPERCCLK}	VSCALE2	—	—	48	MHz
		VSCALE0	—	—	20	MHz

4.1.9.3 Low-Frequency RC Oscillator (LFRCO)

Table 4.13. Low-Frequency RC Oscillator (LFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	f _{LFRCO}	ENVREF ² = 1	TBD	32.768	TBD	kHz
		ENVREF ² = 1, T > 85 °C	TBD	32.768	TBD	kHz
		ENVREF ² = 0	TBD	32.768	TBD	kHz
Startup time	t _{LFRCO}		—	500	—	μs
Current consumption ¹	I _{LFRCO}	ENVREF = 1 in CMU_LFRCOCTRL	—	370	—	nA
		ENVREF = 0 in CMU_LFRCOCTRL	—	520	—	nA

Note:

1. Block is supplied by AVDD if ANASW = 0, or DVDD if ANASW=1 in EMU_PWRCTRL register.

2. In CMU_LFRCOCTRL register.

4.1.9.4 High-Frequency RC Oscillator (HFRCO)

Table 4.14. High-Frequency RC Oscillator (HFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency accuracy	$f_{\text{HFRCO_ACC}}$	At production calibrated frequencies, across supply voltage and temperature	TBD	—	TBD	%
Start-up time	t_{HFRCO}	$f_{\text{HFRCO}} \geq 19 \text{ MHz}$	—	300	—	ns
		$4 < f_{\text{HFRCO}} < 19 \text{ MHz}$	—	1	—	μs
		$f_{\text{HFRCO}} \leq 4 \text{ MHz}$	—	2.5	—	μs
Current consumption on all supplies	I_{HFRCO}	$f_{\text{HFRCO}} = 48 \text{ MHz}$	—	258	TBD	μA
		$f_{\text{HFRCO}} = 38 \text{ MHz}$	—	218	TBD	μA
		$f_{\text{HFRCO}} = 32 \text{ MHz}$	—	182	TBD	μA
		$f_{\text{HFRCO}} = 26 \text{ MHz}$	—	156	TBD	μA
		$f_{\text{HFRCO}} = 19 \text{ MHz}$	—	130	TBD	μA
		$f_{\text{HFRCO}} = 16 \text{ MHz}$	—	112	TBD	μA
		$f_{\text{HFRCO}} = 13 \text{ MHz}$	—	101	TBD	μA
		$f_{\text{HFRCO}} = 7 \text{ MHz}$	—	80	TBD	μA
		$f_{\text{HFRCO}} = 4 \text{ MHz}$	—	29	TBD	μA
		$f_{\text{HFRCO}} = 2 \text{ MHz}$	—	26	TBD	μA
		$f_{\text{HFRCO}} = 1 \text{ MHz}$	—	24	TBD	μA
		$f_{\text{HFRCO}} = 40 \text{ MHz, DPLL enabled}$	—	393	TBD	μA
		$f_{\text{HFRCO}} = 32 \text{ MHz, DPLL enabled}$	—	313	TBD	μA
		$f_{\text{HFRCO}} = 16 \text{ MHz, DPLL enabled}$	—	180	TBD	μA
		$f_{\text{HFRCO}} = 4 \text{ MHz, DPLL enabled}$	—	46	TBD	μA
		$f_{\text{HFRCO}} = 1 \text{ MHz, DPLL enabled}$	—	33	TBD	μA
Coarse trim step size (% of period)	$SS_{\text{HFRCO_COARSE}}$		—	0.8	—	%
Fine trim step size (% of period)	$SS_{\text{HFRCO_FINE}}$		—	0.1	—	%
Period jitter	PJ_{HFRCO}		—	0.2	—	% RMS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency limits	$f_{\text{HFRCO_BAND}}$	FREQRANGE = 0, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 3, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 6, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 7, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 8, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 10, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 11, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 12, FINETUNING = 0	TBD	—	TBD	MHz
		FREQRANGE = 13, FINETUNING = 0	TBD	—	TBD	MHz

4.2.1 Supply Current

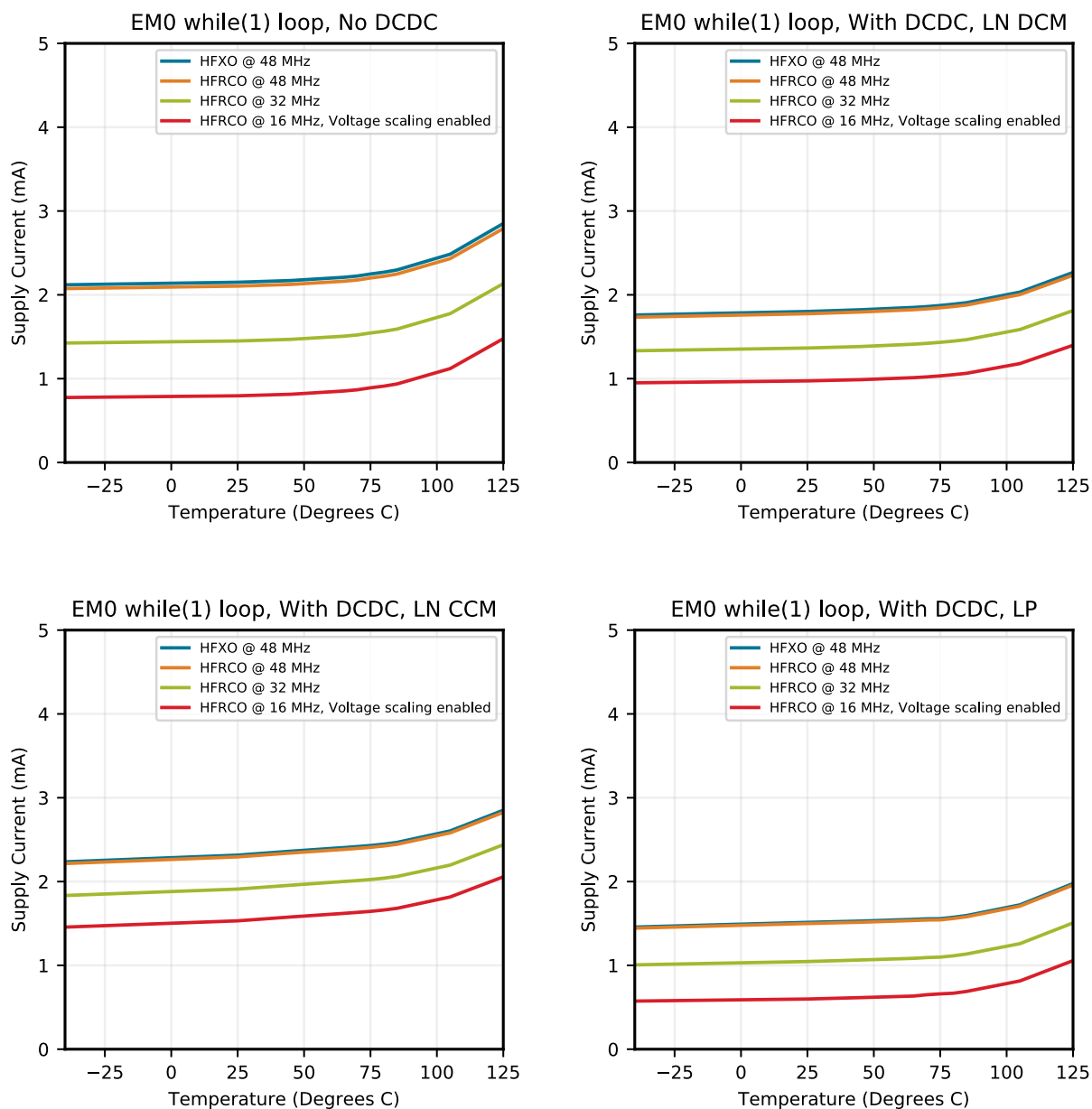


Figure 4.3. EM0 Active Mode Typical Supply Current vs. Temperature

5. Pin Definitions

5.1 EFM32TG11B5xx in QFP80 Device Pinout

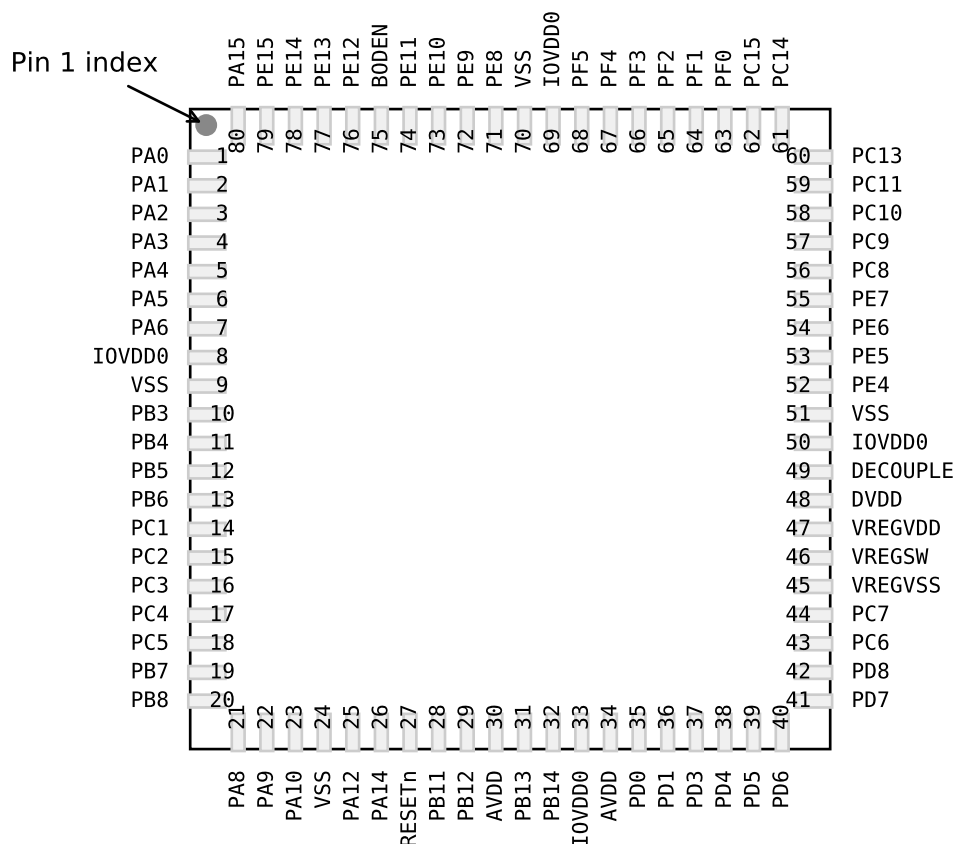


Figure 5.1. EFM32TG11B5xx in QFP80 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.1. EFM32TG11B5xx in QFP80 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
PA6	7	GPIO	IOVDD0	8 33 50 69	Digital IO power supply 0.

5.3 EFM32TG11B5xx in QFP64 Device Pinout

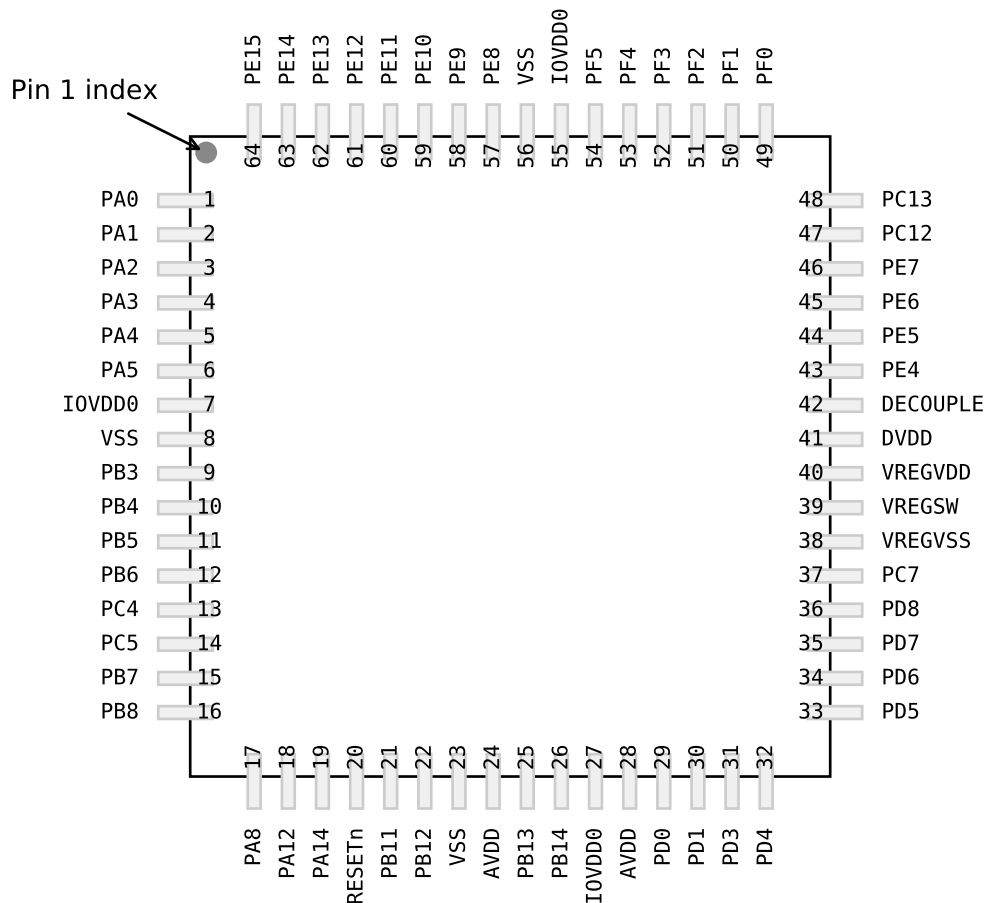


Figure 5.3. EFM32TG11B5xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.3. EFM32TG11B5xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 27 55	Digital IO power supply 0.	VSS	8 23 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

5.6 EFM32TG11B5xx in QFN64 Device Pinout

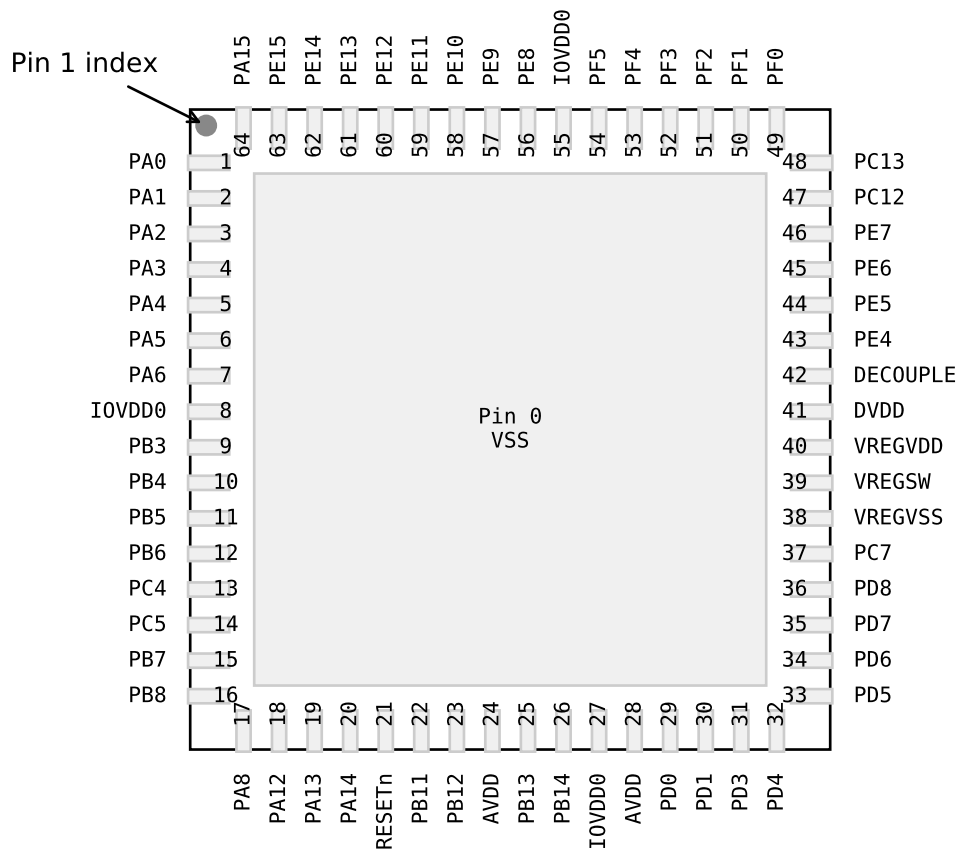


Figure 5.6. EFM32TG11B5xx in QFN64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.6. EFM32TG11B5xx in QFN64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
VREGVSS	0 38	Voltage regulator VSS	PA0	1	GPIO
PA1	2	GPIO	PA2	3	GPIO
PA3	4	GPIO	PA4	5	GPIO
PA5	6	GPIO	PA6	7	GPIO
IOVDD0	8 27 55	Digital IO power supply 0.	PB3	9	GPIO

5.7 EFM32TG11B3xx in QFN64 Device Pinout

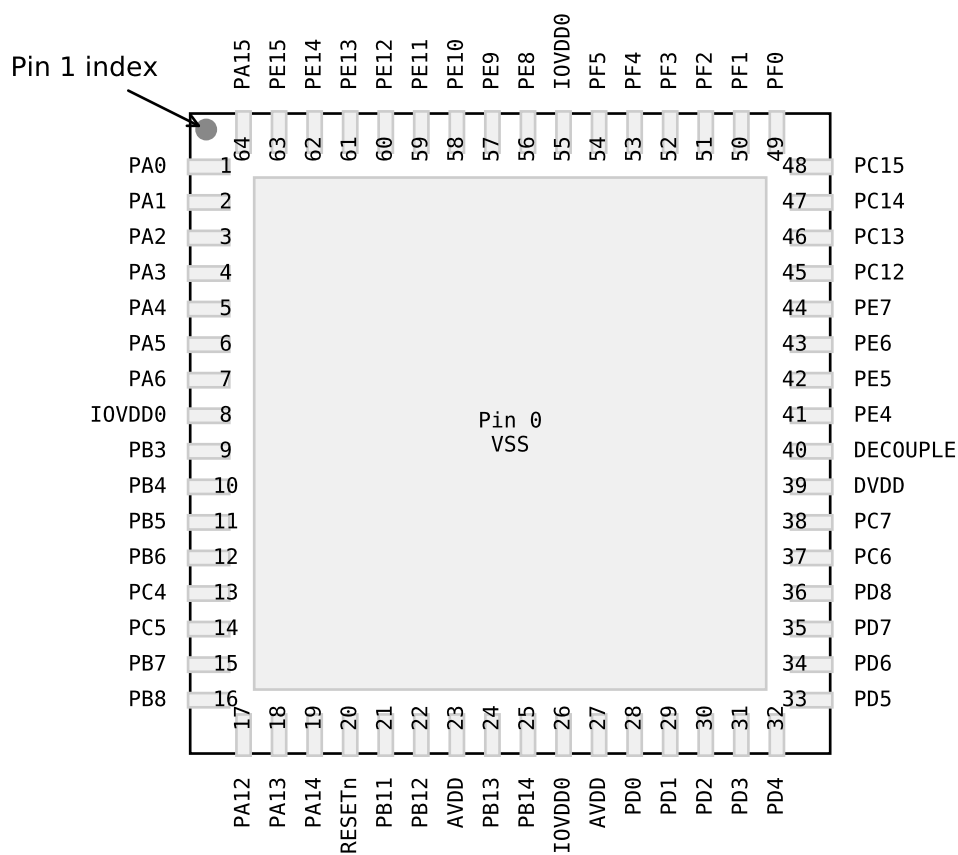


Figure 5.7. EFM32TG11B3xx in QFN64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.7. EFM32TG11B3xx in QFN64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
VREGVSS	0	Voltage regulator VSS	PA0	1	GPIO
PA1	2	GPIO	PA2	3	GPIO
PA3	4	GPIO	PA4	5	GPIO
PA5	6	GPIO	PA6	7	GPIO
IOVDD0	8 26 55	Digital IO power supply 0.	PB3	9	GPIO
PB4	10	GPIO	PB5	11	GPIO

5.9 EFM32TG11B5xx in QFP48 Device Pinout

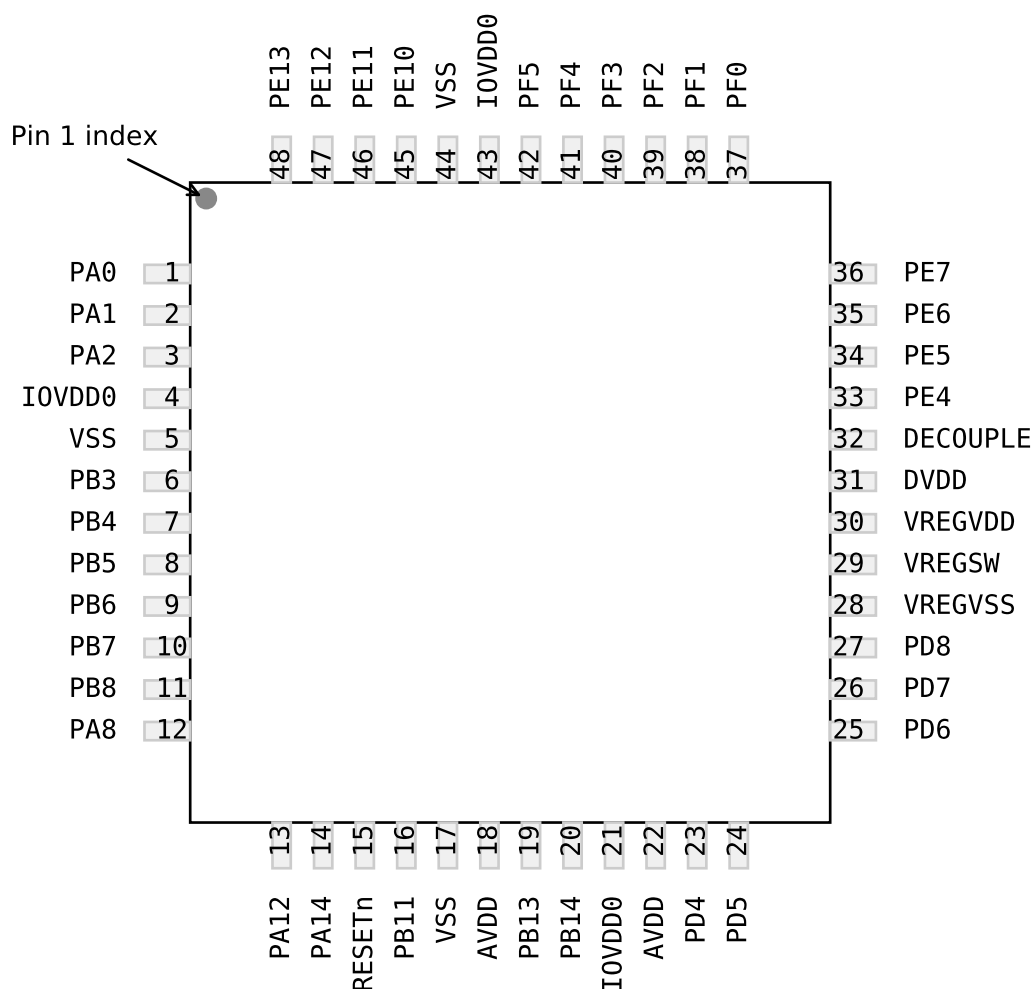


Figure 5.9. EFM32TG11B5xx in QFP48 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.9. EFM32TG11B5xx in QFP48 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	IOVDD0	4 21 43	Digital IO power supply 0.
VSS	5 17 44	Ground	PB3	6	GPIO
PB4	7	GPIO	PB5	8	GPIO
PB6	9	GPIO	PB7	10	GPIO

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB8	11	GPIO	PA8	12	GPIO
PA12	13	GPIO	PA14	14	GPIO
RESETn	15	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB11	16	GPIO
AVDD	18 22	Analog power supply.	PB13	19	GPIO
PB14	20	GPIO	PD4	23	GPIO
PD5	24	GPIO	PD6	25	GPIO
PD7	26	GPIO	PD8	27	GPIO
VREGVSS	28	Voltage regulator VSS	VREGSW	29	DCDC regulator switching node
VREGVDD	30	Voltage regulator VDD input	DVDD	31	Digital power supply.
DECOUPLE	32	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PE4	33	GPIO
PE5	34	GPIO	PE6	35	GPIO
PE7	36	GPIO	PF0	37	GPIO (5V)
PF1	38	GPIO (5V)	PF2	39	GPIO
PF3	40	GPIO	PF4	41	GPIO
PF5	42	GPIO	PE10	45	GPIO
PE11	46	GPIO	PE12	47	GPIO
PE13	48	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
OPA3_N	0: PC7		Operational Amplifier 3 external negative input.
OPA3_OUT	0: PD1		Operational Amplifier 3 output.
OPA3_P	0: PC6		Operational Amplifier 3 external positive input.
PCNT0_S0IN	0: PC13 2: PC0 3: PD6	4: PA0 6: PB5 7: PB12	Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	0: PC14 2: PC1 3: PD7	4: PA1 6: PB6 7: PB11	Pulse Counter PCNT0 input number 1.
PRS_CH0	0: PA0 1: PF3 2: PC14 3: PF2		Peripheral Reflex System PRS, channel 0.
PRS_CH1	0: PA1 1: PF4 2: PC15 3: PE12		Peripheral Reflex System PRS, channel 1.
PRS_CH2	0: PC0 1: PF5 2: PE10 3: PE13		Peripheral Reflex System PRS, channel 2.
PRS_CH3	0: PC1 1: PE8 2: PE11 3: PA0		Peripheral Reflex System PRS, channel 3.
PRS_CH4	0: PC8 2: PF1		Peripheral Reflex System PRS, channel 4.
PRS_CH5	0: PC9 2: PD6		Peripheral Reflex System PRS, channel 5.
PRS_CH6	0: PA6 1: PB14 2: PE6		Peripheral Reflex System PRS, channel 6.
PRS_CH7	0: PB13 2: PE7		Peripheral Reflex System PRS, channel 7.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
U0_TX	2: PA3 3: PC14	4: PC4 5: PF1 6: PD7	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	0: PE12 1: PE5 2: PC9 3: PC15	4: PB13 5: PA12	USART0 clock input / output.
US0_CS	0: PE13 1: PE4 2: PC8 3: PC14	4: PB14 5: PA13	USART0 chip select input / output.
US0_CTS	0: PE14 2: PC7 3: PC13	4: PB6 5: PB11	USART0 Clear To Send hardware flow control input.
US0_RTS	0: PE15 2: PC6 3: PC12	4: PB5 5: PD6	USART0 Request To Send hardware flow control output.
US0_RX	0: PE11 1: PE6 2: PC10 3: PE12	4: PB8 5: PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	0: PE10 1: PE7 2: PC11 3: PE13	4: PB7 5: PC0	USART0 Asynchronous Transmit. Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	0: PB7 1: PD2 2: PF0 3: PC15	4: PC3 5: PB11 6: PE5	USART1 clock input / output.
US1_CS	0: PB8 1: PD3 2: PF1 3: PC14	4: PC0 5: PE4	USART1 chip select input / output.
US1_CTS	1: PD4 2: PF3 3: PC6	4: PC12 5: PB13	USART1 Clear To Send hardware flow control input.
US1_RTS	1: PD5 2: PF4 3: PC7	4: PC13 5: PB14	USART1 Request To Send hardware flow control output.
US1_RX	0: PC1 1: PD1 2: PD6	4: PC2 5: PA0 6: PA2	USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	0: PC0 1: PD0 2: PD7	4: PC1 5: PF2 6: PA14	USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
VDAC0_OUT0 / OPA0_OUT	0: PB11		Digital to Analog Converter DAC0 output channel number 0.
VDAC0_OUT0ALT / OPA0_OUTALT	0: PC0 1: PC1 2: PC2 3: PC3	4: PD0	Digital to Analog Converter DAC0 alternative output for channel 0.
VDAC0_OUT1 / OPA1_OUT	0: PB12		Digital to Analog Converter DAC0 output channel number 1.
VDAC0_OUT1ALT / OPA1_OUTALT	0: PC12 1: PC13 2: PC14 3: PC15	4: PD1	Digital to Analog Converter DAC0 alternative output for channel 1.
WTIM0_CC0	0: PE4 1: PA6	4: PC15 6: PB3 7: PC1	Wide timer 0 Capture Compare input / output channel 0.
WTIM0_CC1	0: PE5	4: PF0 6: PB4 7: PC2	Wide timer 0 Capture Compare input / output channel 1.
WTIM0_CC2	0: PE6	4: PF1 6: PB5 7: PC3	Wide timer 0 Capture Compare input / output channel 2.
WTIM0_CDTI0	0: PE10 2: PA12	4: PD4	Wide timer 0 Complimentary Dead Time Insertion channel 0.
WTIM0_CDTI1	0: PE11 2: PA13	4: PD5	Wide timer 0 Complimentary Dead Time Insertion channel 1.
WTIM0_CDTI2	0: PE12 2: PA14	4: PD6	Wide timer 0 Complimentary Dead Time Insertion channel 2.
WTIM1_CC0	0: PB13 1: PD2 2: PD6 3: PC7	5: PE7	Wide timer 1 Capture Compare input / output channel 0.
WTIM1_CC1	0: PB14 1: PD3 2: PD7	4: PE4	Wide timer 1 Capture Compare input / output channel 1.
WTIM1_CC2	0: PD0 1: PD4 2: PD8	4: PE5	Wide timer 1 Capture Compare input / output channel 2.

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6.2 TQFP80 PCB Land Pattern

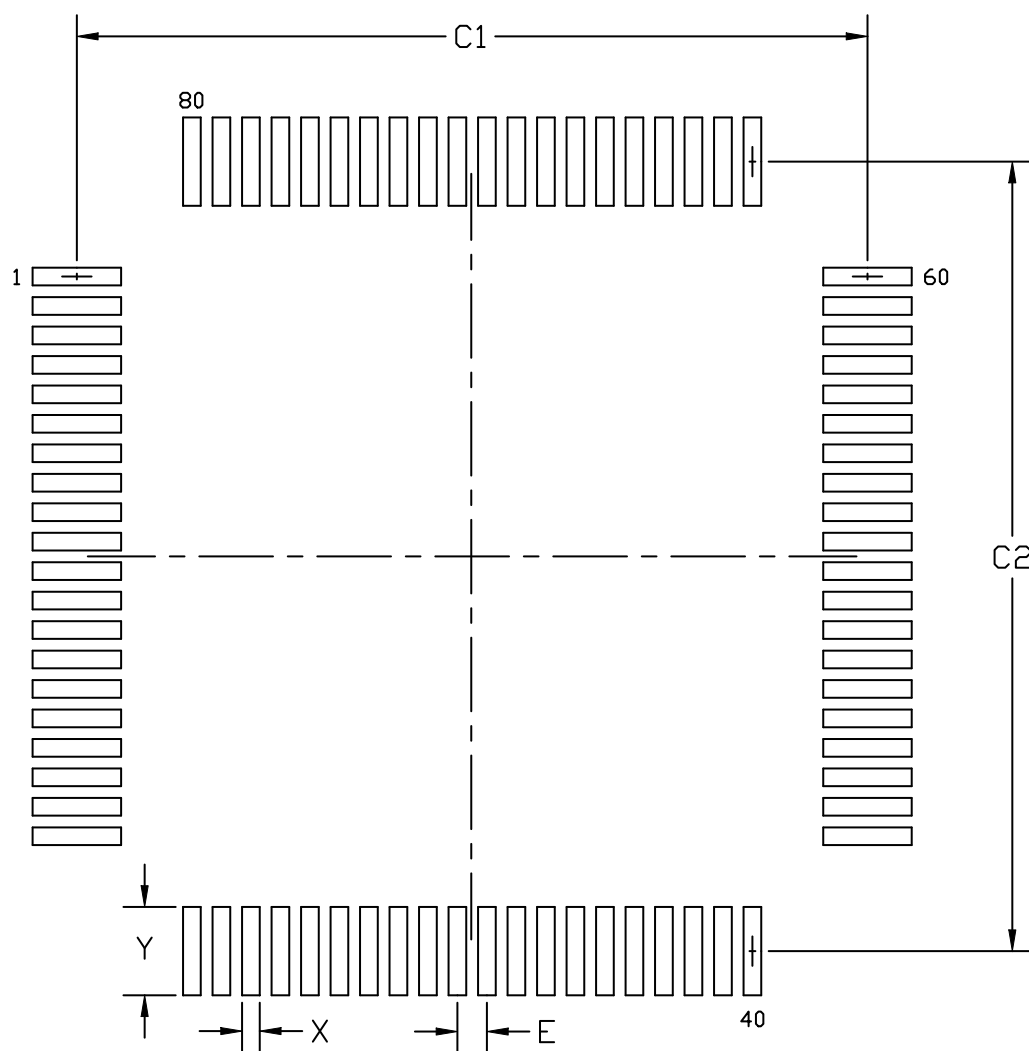


Figure 6.2. TQFP80 PCB Land Pattern Drawing

7.2 QFN80 PCB Land Pattern

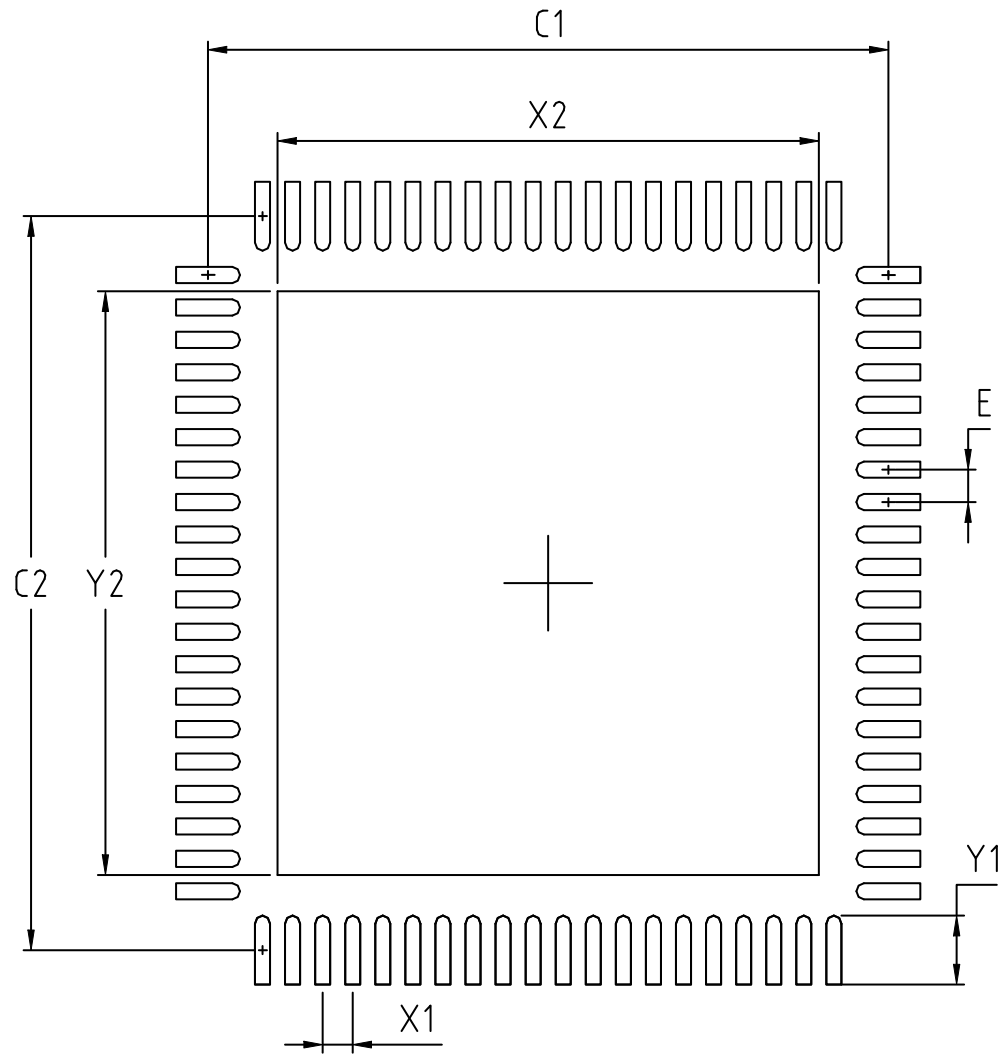


Figure 7.2. QFN80 PCB Land Pattern Drawing

9. QFN64 Package Specifications

9.1 QFN64 Package Dimensions

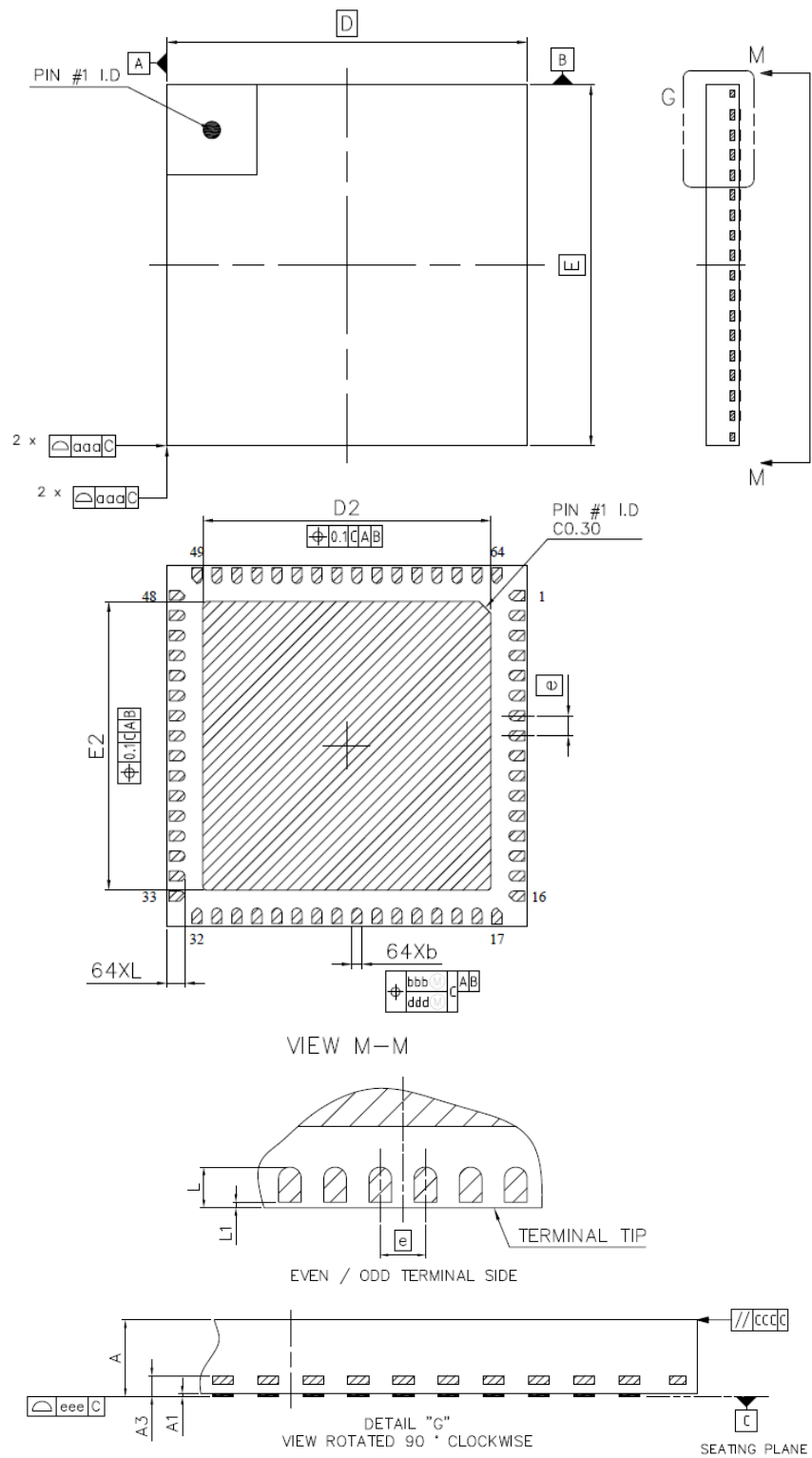


Figure 9.1. QFN64 Package Drawing

Table 9.2. QFN64 PCB Land Pattern Dimensions

Dimension	Typ
C1	8.90
C2	8.90
E	0.50
X1	0.30
Y1	0.85
X2	7.30
Y2	7.30

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05mm.
4. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.
5. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
6. The stencil thickness should be 0.125 mm (5 mils).
7. The ratio of stencil aperture to land pad size can be 1:1 for all pads.
8. A 3x3 array of 1.45 mm square openings on a 2.00 mm pitch can be used for the center ground pad.
9. A No-Clean, Type-3 solder paste is recommended.
10. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

10.3 TQFP48 Package Marking



Figure 10.3. TQFP48 Package Marking

The package marking consists of:

- P P P P P P P P P P – The part number designation.
- T T T T T T – A trace or manufacturing code. The first letter is the device revision.
- Y Y – The last 2 digits of the assembly year.
- W W – The 2-digit workweek when the device was assembled.